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*Marc Desmulliez, Suzanne Costello, Heriot-Watt University, Edinburgh, UK., Wolfgang Reinert, Fraunhofer Institute for Silicon Technology
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*J r mie BOUCHAUD, IHS iSuppli, Munich, Germany, Jean Michel Karam, MEMSCAP, Bernin, France, Sean Neylon, Colibrys, Neuch tel,
Switzerland, Thierry Brisard, NEOSENS, Toulouse, France*

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